

Features

- ESD protection for one line with bi-directional
- Provide transient protection for one line to IEC 61000-4-2 (ESD) ±18kV (air), ±18kV (contact) IEC 61000-4-4 (EFT) 50A (5/50ns) Cable Discharge Event (CDE)
- Suitable for, 3.3V and below, operating voltage applications
- 01005 small CSP package saves board space
- Protect one I/O line or one power line
- Fast turn-on and low clamping voltage
- Solid-state silicon-avalanche and active circuit triggering technology
- Green part

Applications

- Mobile phones
- Hand held portable applications
- Computer interfaces protection
- Microprocessors protection
- Serial and parallel port protection
- Control signal lines protection
- Power lines on PCB protection
- Fingerprint

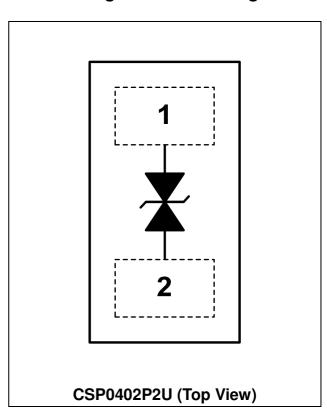
Description

AZ5C23-01B is a design which includes one bi-directional ESD rated clamping cell to protect one power line, or one control line, or one low-speed data line in an electronic system. The AZ5C23-01B has been specifically designed to protect sensitive components which are connected to power and control lines from over-voltage damage and latch-up caused by Electrostatic Discharging (ESD), Electrical Fast Transients (EFT), and Cable Discharge Event (CDE).

AZ5C23-01B is a unique design which includes proprietary clamping cell in a single package. During transient conditions, the proprietary clamping cell prevents over-voltage on the power line or control/data lines, protecting downstream components.

AZ5C23-01B may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

Circuit Diagram / Pin Configuration



SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C, unless otherwise specified)				
PARAMETER	SYMBOL	RATING	UNIT	
Operating Supply Voltage	V_{DC}	±3.6	V	
ESD per IEC 61000-4-2 (Air)	V _{ESD-1}	±18	kV	
ESD per IEC 61000-4-2 (Contact)	V_{ESD-2}	±18		
Lead Soldering Temperature	T _{SOL}	260 (10 sec.)	°C	
Operating Temperature	T _{OP}	-55 to +125	°C	
Storage Temperature	T _{STO}	-55 to +150	°C	

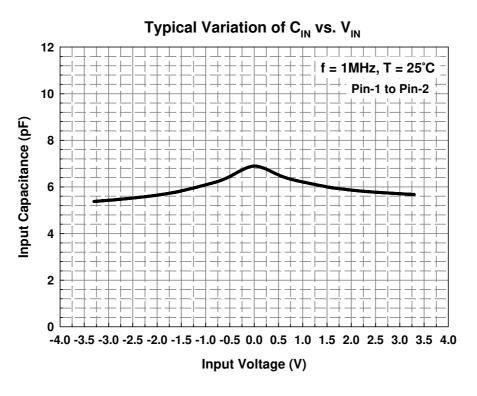
ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Reverse Stand-Off Voltage	V_{RWM}	T = 25 °C.	-3.3		3.3	٧
Reverse Leakage Current	I _{Leak}	$V_{RWM} = \pm 3.3 V, T = 25 ^{\circ}C.$			100	nA
Reverse Breakdown Voltage	V_{BV}	I _{BV} = 1mA, T = 25 °C.	4.0		6.8	V
ESD Clamping Voltage (Note 1)	$V_{\text{CL-ESD}}$	IEC 61000-4-2 +8kV (I _{TLP} = 16A), Contact mode, T = 25 °C.		5.8		V
ESD Dynamic Turn-on Resistance	$R_{dynamic}$	IEC 61000-4-2 0~+8kV, Contact mode, T = 25 °C.		0.1		Ω
Channel Input Capacitance	C_{IN}	$V_R = 0V$, $f = 1MHz$, $T = 25$ °C.		7	10	pF

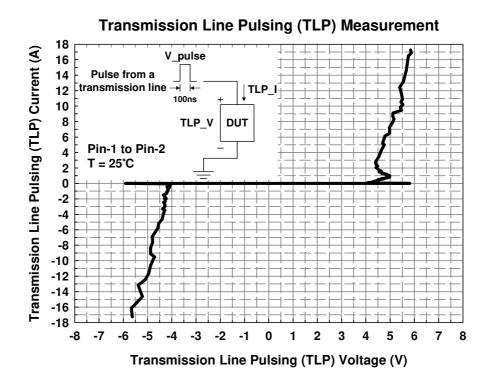
Note 1: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.

TLP conditions: $Z_0 = 50\Omega$, $t_p = 100$ ns, $t_r = 1$ ns.



Typical Characteristics







Application Information

The AZ5C23-01B is designed to protect one line against system ESD/EFT/Cable Discharge pulses by clamping it to an acceptable reference. It provides bi-directional protection.

The usage of the AZ5C23-01B is shown in Fig. 1. Protected line, such as data line, control line, or power line, is connected at pin 1. The pin 2 is connected to a ground plane on the board. In order to minimize parasitic inductance in the board traces, all path lengths connected to the pins of AZ5C23-01B should be kept as short as possible.

In order to obtain enough suppression of ESD induced transient, a good circuit board is critical. Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ5C23-01B.
- Place the AZ5C23-01B near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

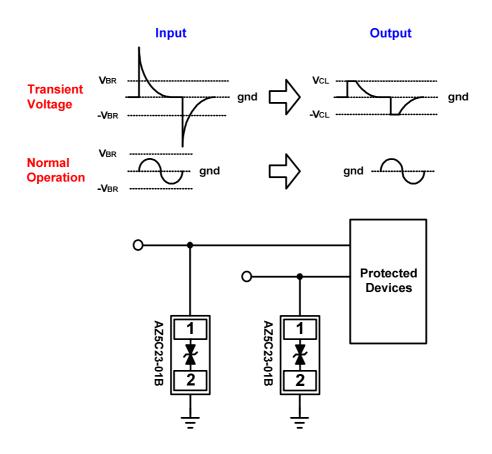
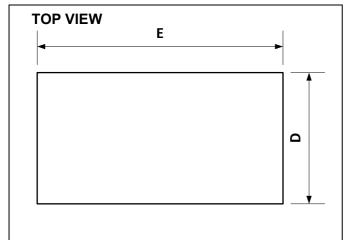


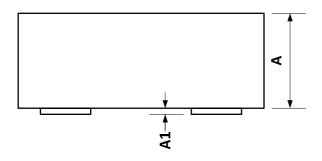
Fig. 1 ESD protection scheme by using AZ5C23-01B



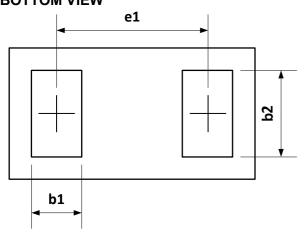
Mechanical Details CSP0402P2U PACKAGE DIAGRAMS



SIDE VIEW



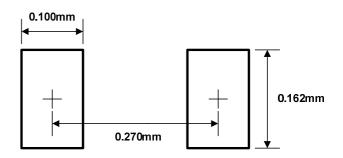
BOTTOM VIEW



PACKAGE DIMENSIONS

SYMBOL	MILLIMETERS			
	MIN.	NOM.	MAX.	
E	0.415	0.440	0.465	
D	0.210	0.235	0.260	
Α	0.145	0.170	0.195	
A 1	0.008	0.011	0.014	
b1	0.084	0.090	0.096	
b2	0.149	0.155	0.161	
e1	0.270BSC			

LAND LAYOUT



Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.



MARKING CODE

Part Number	Marking Index	Device Code and Location		
AZ5C23-01B.R7G (Green Part)	Top View Side)	(Bottom View Side)		

Notes

- 1. Green means Pb-free, RoHS, and Halogen free compliant.
- 2. The marking index is on the top view side of the device. The device code is on the pad side (bottom view side).

Ordering Information

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ5C23-01B.R7G	Green	T/R	7 inch	15,000/reel	4 reels = 60,000/box	6 boxes = 360,000/carton

Revision History

Revision	Modification Description
Revision 2018/03/13	Formal Release.

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